

# STTH3L06

## TURBO 2 ULTRAFAST HIGH VOLTAGE RECTIFIER

**Table 1: Main Product Characteristics** 

I <sub>F(AV)</sub>	3 A
V <sub>RRM</sub>	600 V
I <sub>R</sub> (max)	100 μΑ
T <sub>j</sub>	175°C
V <sub>F</sub> (typ)	0.85 V
t <sub>rr</sub> (typ)	60 ns

#### **FEATURES AND BENEFITS**

- Ultrafast switching
- Low forward voltage drop
- Low thermal resistance
- Low leakage current (platinium doping)

#### **DESCRIPTION**

The STTH3L06, which is using ST Turbo 2 600V technology, is specially suited as boost diode in discontinuous or critical mode power factor corrections.

This device is intended for use as a free wheeling diode in power supplies and other power switching applications.

**Table 2: Order Codes** 

Part Number	Marking
STTH3L06	STTH3L06
STTH3L06RL	STTH3L06
STTH3L06B	STTH3L06B
STTH3L06B-TR	STTH3L06B
STTH3L06U	3L6U
STTH3L06S	S06

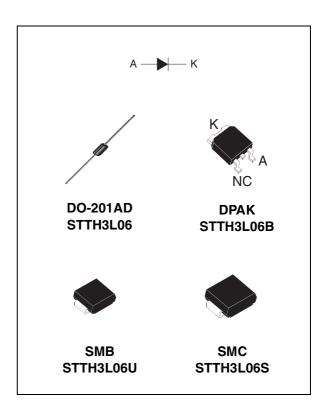


Table 3: Absolute Ratings (limiting values)

Symbol	Paramet	Value	Unit		
V <sub>RRM</sub>	Repetitive peak reverse voltage			600	V
I <sub>F(RMS)</sub>	RMS forward current	DO-201AD / S	SMB / SMC	10	Α
, ,		DPAK		6	
I <sub>F(AV)</sub>	Average forward current	DO-201AD	TI = 100°C	3	Α
, ,	$\delta = 0.5$	DPAK	TI = 155°C		
		SMB	TI = 80°C		
		SMC	TI = 100°C		
I <sub>FSM</sub>	Surge non repetitive forward current	DO-201AD	tp = 10ms	70	Α
		SMB / SMC	sinusoidal	60	
		DPAK		40	
T <sub>stg</sub>	Storage temperature range			-65 to + 175	°C
T <sub>j</sub>	Maximum operating junction temperat	ure		175	°C

#### **Table 4: Thermal Parameters**

Symbol	Parameter	Parameter			
R <sub>th(j-l)</sub>	Junction to lead DO-201AD L = 10 mm		20	°C/W	
		DPAK	5.5		
		SMB	25		
		SMC	20		
R <sub>th(j-a)</sub>	Junction to ambient (see fig. 13)	DO-201AD L = 10 mm	75	°C/W	

### **Table 5: Static Electrical Characteristics**

Symbol	Parameter	Test conditions		Min.	Тур	Max.	Unit
I <sub>R</sub>	Reverse leakage current	T <sub>j</sub> = 25°C	$V_R = V_{RRM}$			3	μA
		T <sub>j</sub> = 150°C			15	100	
V <sub>F</sub>	Forward voltage drop	$T_j = 25^{\circ}C$	I <sub>F</sub> = 3A			1.3	V
		T <sub>j</sub> = 150°C			0.85	1.05	

To evaluate the conduction losses use the following equation:  $P = 0.89 \times I_{F(AV)} + 0.055 I_{F}^{2}(RMS)$ 

### **Table 6: Dynamic Characteristics**

Symbol	Parameter	Test conditions			Тур	Max.	Unit
t <sub>rr</sub>	Reverse recovery time	T <sub>j</sub> = 25°C	$I_F = 1A dI_F/dt = -50 A/\mu s V_R = 30V$		60	85	ns
t <sub>fr</sub>	Forward recovery time	T <sub>j</sub> = 25°C	$I_F = 3A$ $dI_F/dt = 100 A/\mu s$ $V_{FR} = 1.1 \times V_{Fmax}$			100	ns
V <sub>FP</sub>	Forward recovery voltage		$I_F = 3A$ $dI_F/dt = 100 A/\mu s$			7.5	V

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Figure 1: Conduction losses versus average current

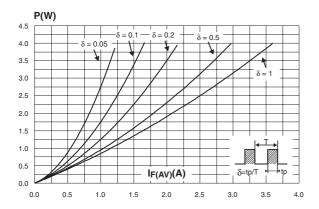


Figure 3: Relative variation of thermal impedance junction ambient versus pulse duration (epoxy printed circuit FR4,  $L_{leads} = 10$ mm,  $S_{CU}=1$ cm<sup>2</sup>)

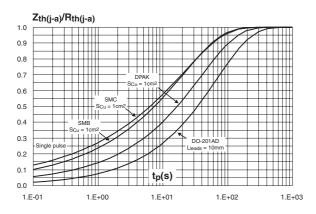


Figure 5: Reverse recovery time versus dl<sub>F</sub>/dt (typical values)

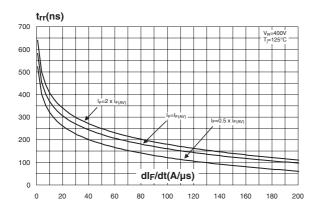


Figure 2: Forward voltage drop versus forward current

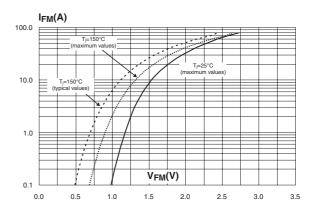


Figure 4: Peak reverse recovery current versus dl<sub>F</sub>/dt (typical values)

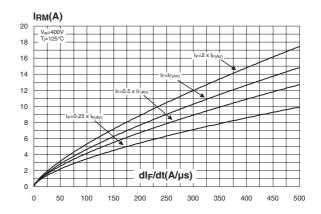
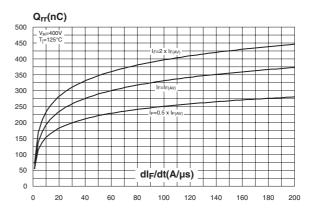


Figure 6: Reverse recovery charges versus dI<sub>F</sub>/dt (typical values)



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Figure 7: Softness factor versus d<sub>IF</sub>/dt (typical values)

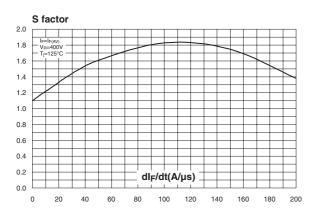


Figure 9: Transient peak forward voltage versus dl<sub>F</sub>/dt (typical values)

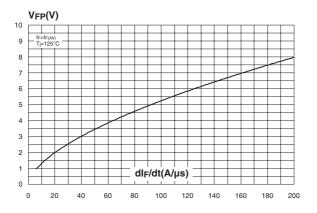


Figure 11: Junction capacitance versus reverse voltage applied (typical values)

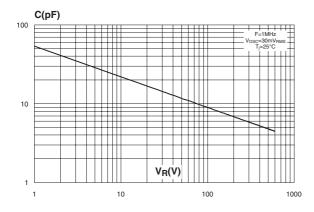


Figure 8: Relative variations of dynamic parameters versus junction temperature

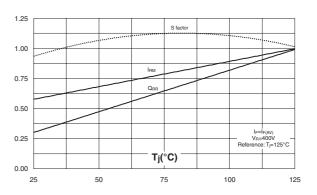


Figure 10: Forward recovery time versus  $dI_F/dt$  (typical values)

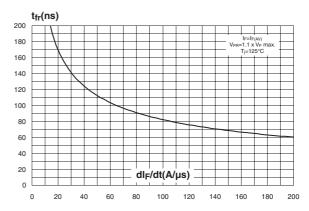
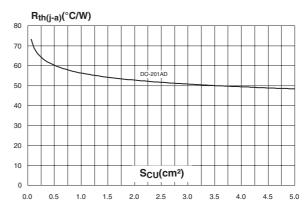


Figure 12: Thermal resistance junction to ambient versus copper surface under lead (epoxy FR4,  $e_{CU}$ =35 $\mu$ m) (DO-201AD)



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Figure 13: Thermal resistance junction to ambient versus copper surface under lead (epoxy FR4,  $e_{CU}$ =35 $\mu$ m) (SMB / SMC)

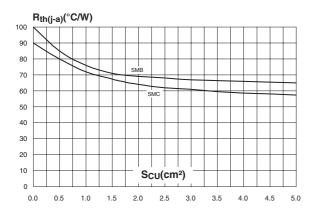


Figure 14: Thermal resistance junction to ambient versus copper surface under tab (epoxy FR4,  $e_{CU}$ =35 $\mu$ m) (DPAK)

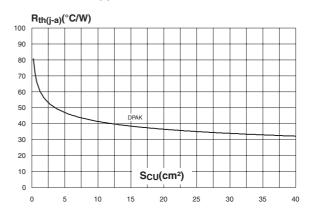


Figure 15: Thermal resistance versus lead length

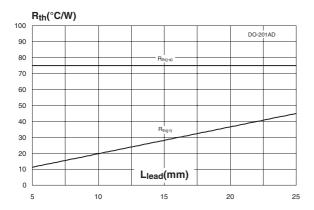
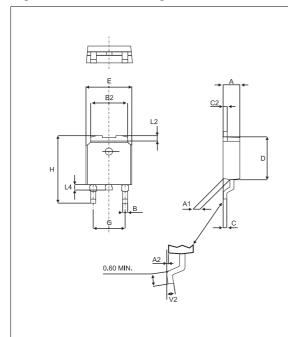
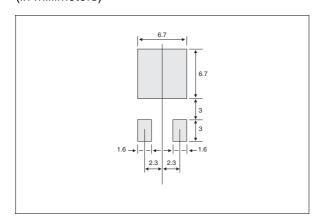


Figure 16: DPAK Package Mechanical Data



		DIMEN	ISIONS	
REF.	Millim	neters	Inc	hes
	Min.	Max	Min.	Max.
Α	2.20	2.40	0.086	0.094
A1	0.90	1.10	0.035	0.043
A2	0.03	0.23	0.001	0.009
В	0.64	0.90	0.025	0.035
B2	5.20	5.40	0.204	0.212
С	0.45	0.60	0.017	0.023
C2	0.48	0.60	0.018	0.023
D	6.00	6.20	0.236	0.244
Е	6.40	6.60	0.251	0.259
G	4.40	4.60	0.173	0.181
Н	9.35	10.10	0.368	0.397
L2	0.80 typ.		0.03	1 typ.
L4	0.60	1.00	0.023	0.039
V2	0°	8°	0°	8°

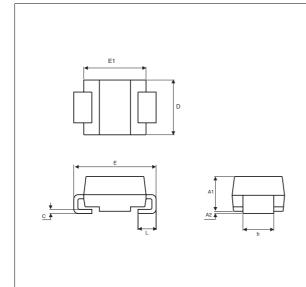
**Figure 17: DPAK Foot Print Dimensions** (in millimeters)



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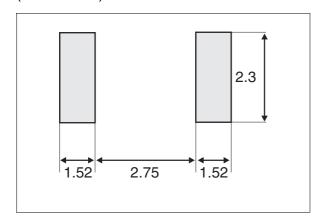
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Figure 18: SMB Package Mechanical Data



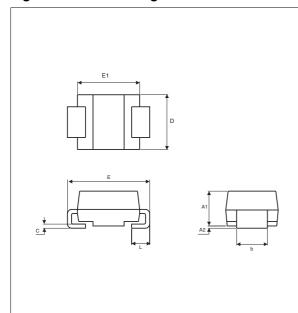
	DIMENSIONS					
REF.	Millin	neters	Inc	hes		
	Min.	Max.	Min.	Max.		
A1	1.90	2.45	0.075	0.096		
A2	0.05	0.20	0.002	0.008		
b	1.95	2.20	0.077	0.087		
С	0.15	0.41	0.006	0.016		
Е	5.10	5.60	0.201	0.220		
E1	4.05	4.60	0.159	0.181		
D	3.30	3.95	0.130	0.156		
L	0.75	1.60	0.030	0.063		

Figure 19: SMB Foot Print Dimensions (in millimeters)



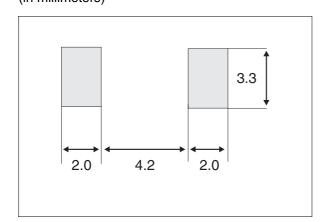
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Figure 20: SMC Package Mechanical Data



	DIMENSIONS				
REF.	F. Millimeters		Inches		
	Min.	Max.	Min.	Max.	
A1	1.90	2.45	0.075	0.096	
A2	0.05	0.20	0.002	0.008	
b	2.90	3.2	0.114	0.126	
С	0.15	0.41	0.006	0.016	
Е	7.75	8.15	0.305	0.321	
E1	6.60	7.15	0.260	0.281	
E2	4.40	4.70	0.173	0.185	
D	5.55	6.25	0.218	0.246	
L	0.75	1.60	0.030	0.063	

Figure 21: SMC Foot Print Dimensions (in millimeters)



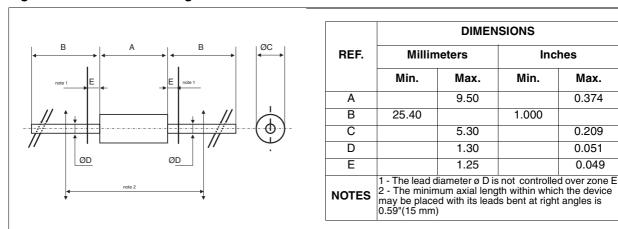


Figure 22: DO-201AD Package Mechanical Data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: <a href="https://www.st.com">www.st.com</a>.

**Table 7: Ordering Information** 

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STTH3L06	STTH3L06	DO-201AD	1.12 g	600	Ammopack
STTH3L06-RL	STTH3L06	DO-201AD	1.12 g	1900	Tape & reel
STTH3L06B	STTH3L06B	DPAK	0.3 g	75	Tubel
STTH3L06B-TR	STTH3L06B	DPAK	0.3 g	2500	Tape & reel
STTH3L06U	3L6U	SMB	0.11 g	2500	Tape & reel
STTH3L06S	S06	SMC	0.243 g	2500	Tape & reel

- Epoxy meets UL94, V0
- Band indicated cathode (DO-201AD)
- Bending method: see application note **AN1471** (DO-201AD)

**Table 8: Revision History** 

Date	Revision	Description of Changes
October-2001	1	First issue
07-Sep-2004	2	SMB, SMC and DPAK packages added
14-Oct-2005	3	Changed marking of STTH3L06U from 3L06U to 3L6U. Added ECOPACK statement

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